



Customer Information Notification

2015050111

Issue Date: 29-May-2015
Effective Date: 01-Jul-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Management Summary

Gain binning will be skipped to create a more efficient and standard testflow omitting superfluous process steps. As a result the Gain binning will not be part anymore of the marking on the product.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Skip Gain binning

Information Notification

Gain binning was applied in the past on special customer request on a part of NXP portfolio. Necessity for Gain binning on a subset of this portfolio is not required anymore (see attached product list). Therefore the Gain binning step and associated marking on the affected products will be skipped. This will create a more efficient and standard testflow omitting superfluous process steps.

Why do we issue this Information Notification

To inform the customer on the change in product marking

Identification of Affected Products

Top side marking

Gain code will not be part anymore of the marking on the product.

Rest of the product marking will remain unchanged

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Hans Buis
Position Process Improvement manager
e-mail address Hans.Buis@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest

possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC
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BLF7G22LS-130,112	934063501112
BLF8G10LS-160,118	934065908118
BLF7G22LS-130,112	934063501112